

IN THE SPECIFICATION:

Please replace the original 5th paragraph on page 7, starting with "A metal film" and ending with "wiring patterns 15," with the following replacement paragraph:

--A metal film 16 is provided on a peripheral portion on the main surface of the piezoelectric substrate 11A. The ~~meal~~ metal film 16 is located further out than the IDT 13 and the pads 14 so as to surround these patterns. Similarly, a metal film 4 is provided on a peripheral portion on the main surface of the base substrate 2A. The metal films 16 and 4 are joined so that a cavity 9 defined by the piezoelectric substrate 11A and the base substrate 2A can be hermetically sealed. In the cavity 9 thus sealed hermetically, there are the IDT 13, the electrode pads 14 and the wiring patterns 15. --